ALMIT SRC HM1 RMA V16L SOLDER PASTE

Almit Technology have been developing innovative soldering products for many years. Almit SRC HM1 RMA V16L solder paste is a high quality, no clean solder paste designed for use in surface mount assembly applications where users may need to print paste on very small outline pads such as when assembling 12 thou QFP's or 0201 chips. The importance of using a high quality solder paste should not be underestimated. The most cost-effective process is realised by making good quality solder joints as quickly as possible. Almit SRC HM1 RMA V16L solder paste enables users to work within a wide process window whilst achieving very high first time pass rates.

FEATURES:-

1) The paste is capable of printing 0.4mm pitch and the **TIME BETWEEN PRINTS** can be as much as 1 hour

2) **PRINT TO PLACE** delay as much as 8 hours

3) Component **PLACEMENT TO REFLOW,** up to 16 hours

4) **SUPERIOR FLUX WETTABILITY** guarantees bright, shiny joints and full pcb pad coverage on gold and organic coatings. The **UNIQUE** flux action during reflow guarantees void free joints on BGA packages

5) The flux residue has a **HIGH S.I.R.** which guarantees high finished product reliability

6) Post reflow flux residue does **NOT** need to be cleaned off the pcb

7) Small amount of post reflow flux residue does not hinder in-circuit testing, thus **FALSE READINGS** are **ELIMINATED**

8) The **EXPENSE** and complication of Nitrogen Re-Flow systems are **AVOIDED**

9) Its **SUPERIOR PRINTABILITY** eliminates bridges and ensures stable, high strength joints

10) **V16L** is capable of print speeds up to **140mm/sec**

11) **V16L** exceeds **Bellcore TR – NWT – 00078** Standard

12) **V16L** is supplied to J-Std 004/5/6 IPC-TM 650 Approval

TYPICAL APPLICATIONS:-

Almit SRC HM1 RMA V16L can be used in ALL areas of Electronic Surface Mount Assembly such as Computers, Audio and Video equipment, Mobile Telephones, and Automotive Electronics but is especially designed for very fine pitch assembly.

CHARACTERISTICS:-

ITEMS	HM1 – RMA V16L	TEST METHODS
Solder Alloy	Sn62	QQS-571-F
Particle Size	20-38 microns	IPC-TM-650
Water Extract Resistance	> 100,000 Ω/cm	QQS-571-F
Surface Insulation Resistance	≧ 1 x 10^{12} Ω	JIS-Z-3197
Anti - Humidity (Under an applied voltage)	≧ 1 x 10^{12} Ω	JIS-Z -3197
Spreadability	≧ 80%	JIS-Z-3197
Flux Type	L1	J-STD-004

ADDITIONAL INFORMATION:-

Other documentation available for this product is:

ALMIT SRC HM1 RMA V16L MATERIAL SAFETY DATA SHEET
ALMIT SRC HM1 RMA V16L SPECIFICATION
ALMIT SRC HM1 RMA V16L EVALUATION AS PER J-STD
ALMIT RECOMMENDED REFLOW PROFILE

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